Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**.047”**

**.047”**

**ANODE**

**.030”**

**CHIP BACK IS CATHODE**

**Top Material: Au**

**Backside Material: TiNiAg**

**Bond Pad Size (Anode): .030” X .030”**

**Backside Potential: Cathode**

**APPROVED BY: DK DIE SIZE .047” X .047” DATE: 10/21/21**

**MFG: ON SEMI / MOTOROLA THICKNESS .016” P/N: 1N4004**

**DG 10.1.2**

#### Rev B, 7/19/02